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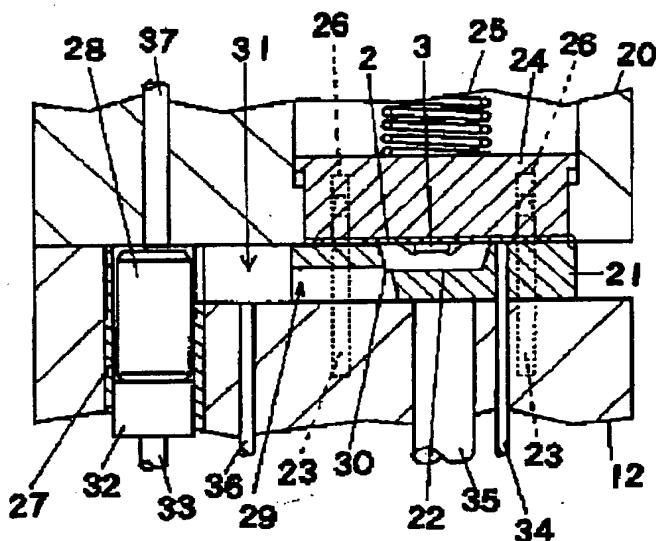
APPLICATION DATE : 22-12-93
APPLICATION NUMBER : 05324628

APPLICANT : MATSUSHITA ELECTRIC IND CO LTD;

INVENTOR : NISHINAKA TERUAKI;

INT. CL : H01L 21/56

**TITLE : EQUIPMENT AND METHOD OF
MANUFACTURING ELECTRONIC
PART**



ABSTRACT : PURPOSE: To provide a means capable of forming a molding body having no flash and an excellent shape in an electronic-part production equipment forming the molding body sealing a chip loaded on a circuit board with a resin.

CONSTITUTION: In a resin sealing device, in which a molding body sealing a chip 3 is loaded on a circuit board 2 is formed by holding a cavity block 21 between a bottom force 12 and a top force 20 and injecting a molten resin into a cavity 22, the cavity 22 is formed to the top face of the cavity block 21, and a groove section 29 is formed to the underside of the cavity block 21. Accordingly, the molten resin of a row resin 28 heated and melted in the pot 27 of the bottom force 12 is press-fitted into the cavity 22 through a runner channel 31 and the groove section 29.

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